



Solder plus Support

NC256 Dipping Flux



Dipping Flux

Features:

- Formulated for PoP Assembly / Sphere Attach
- For use with Pb & Pb-Free
- Halide-Halogen-Free
- Excellent Wetting to ENIG-OSP-ImAg
- Ultra Stable Viscosity Formula for Consistent Volume Transfer

Description:

NC256 Dipping Flux is a no clean flux designed for flux dipping pin or roller transfer applications. NC256 Dipping Flux does not string or tail. It is formulated to separate cleanly for uniform flux application. NC256 Dipping Flux has been engineered to offer excellent activity and wetting characteristics in both lead bearing and lead-free applications. Slump and humidity tolerances found in NC256 Dipping Flux extend the useable life in facilities where the environmental control is not at its optimum.

Flux Application:

- Standard packaging for NC256 Dipping Flux is EFD 10cc syringes. It can be dispensed or used with either linear or rotary style controlled volume dipping equipment or pin transfer systems.
- NC256 Dipping Flux can be used in both linear and ramp-soak-spike reflow profile styles in either leaded or lead-free applications.

Cleaning:

- NC256 Dipping Flux is formulated for residues to be left on the assembly; however it can be cleaned, if necessary, with saponified water or an appropriate solvent cleaner.
- Please refer to the AIM Cleaner Matrix for a list of suitable cleaning materials.

Handling and Storage:

- NC256 Dipping Flux has a refrigerated shelf life of 1 year at 4°C - 12°C (40°F - 55°C).
- The estimated open time of NC256 Dipping Flux on a doctor plate is 7 days.
- NC256 Dipping Flux should be removed from refrigeration 4 hours prior to use.
- Work area should be maintained between 21°C - 26°C (70°F - 80°F), 45-65% Rh – Increased temperature will effect performance.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying Material Safety Data Sheet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Properties:

PARAMETER	VALUE
IPC Classification to J-STD-004	ROLO
Viscosity	Gel-like consistency
Residues	Clear, Colorless

Surface Insulation Resistance:

REFERENCE	PROPERTY	PASS-FAIL CRITERIA	RESULT
IPC-TM-650 method 2.6.3.3. §5.5.1	Control coupons	>1E9 Ω at 96 and 168 h	Pass
J-STD-004 §3.2.4.5.1	Sample coupons	>1E8 Ω at 96 and 168 h	Pass
IPC-TM-650 method 2.6.3.3. §5.5.2	Post-test visual inspection	No corrosion	Pass

The result of the qualification test indicates that the AIM NC256 dipping flux complies with the requirements of IPC TM-650, Method 2.6.3.3 for Surface Insulation Resistance.

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 AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

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